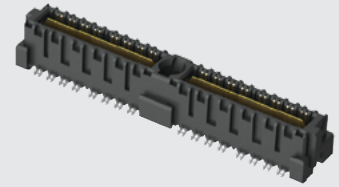


QMS-026-06.75-L-D-A



(0.635 mm) .025"

QMS SERIES

# RUGGED GROUND PLANE HEADER

## SPECIFICATIONS

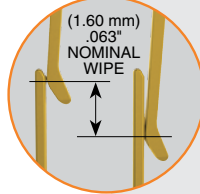
For complete specifications and recommended PCB layouts see [www.samtec.com?QMS](http://www.samtec.com?QMS)

**Insulator Material:**  
Liquid Crystal Polymer  
**Terminal & Ground Plane Material:**  
Phosphor Bronze  
**Plating:**  
Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail)  
**Current Rating:**  
Contact:  
2.6 A per pin  
(1 pin powered per row)  
Ground Plane:  
15.7 A per ground plane  
(1 ground plane powered)  
**Operating Temp:**  
-55 °C to +125 °C  
**Voltage Rating:**  
300 VAC mated with QFS  
**RoHS Compliant:**  
Yes

**Board Mates:**  
QFS

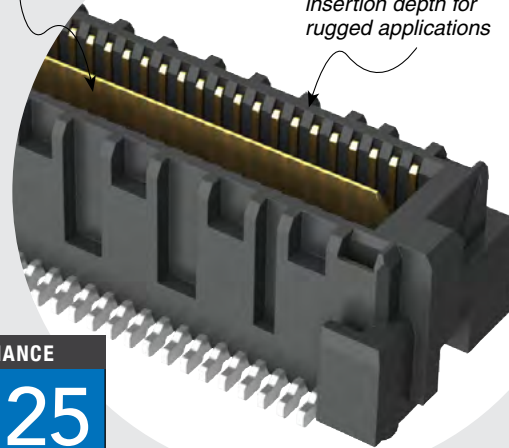
**Cable Mates:**  
6QCD

**Standoffs:**  
SO, JSOM



Integral metal plane for power or ground

Increased insertion depth for rugged applications



## HIGH-SPEED CHANNEL PERFORMANCE

QMS-DP/QFS-DP @ 10 mm Mated Stack Height  
Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

25 Gbps

## ALSO AVAILABLE (MOQ Required)

- Other platings
  - Guide Posts
  - Without PCB Alignment Pins (05.75 and 06.75 only)
  - Hot Pluggable
  - 64 (-DP) and 104 positions per row
- Contact Samtec.

## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max (026-052)  
(0.15 mm) .006" max (078)  
**Board Stacking:**  
For applications requiring more than two connectors per board, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## STANDARDS

- SUMIT™
- PCI/104-Express™

## PROTOCOLS

- 100 GbE
- Fibre Channel
- XAUI
- PCI Express®
- SATA

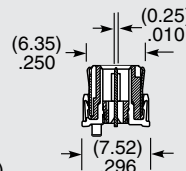
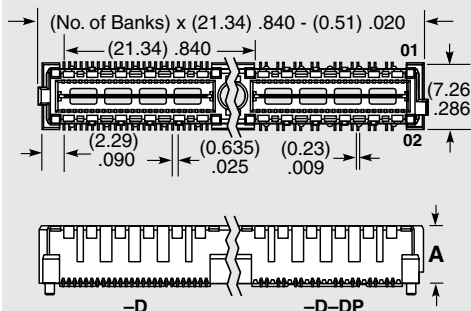
**Note:** Some lengths, styles and options are non-standard, non-returnable.

QMS	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank = -D)	-016, -032, -048 (16 pairs per bank = -D-DP) (-078 & -048 Not available with -09.75 lead style)	-L (-05.75 and -06.75 lead style only) = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended  -D-DP = Differential Pair		-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad

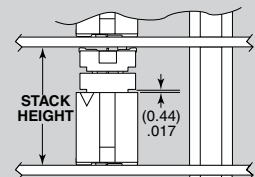
Specify LEAD STYLE from chart

LEAD STYLE	A	MATED HEIGHT*	
		QFS LEAD STYLE -04.25	QFS LEAD STYLE -06.25
-05.75	(5.38) .212	10 mm	12 mm
-06.75	(6.35) .250	11 mm	13 mm
-09.75	(9.35) .368	14 mm	16 mm

\*Processing conditions will affect mated height. See SO Series for board space tolerances.



## APPLICATION



Requires Standoff  
SO-1524-03-01-01-L or JSOM-1524-02 for 15.24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15.24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15.24 mm
PCI/104-Express™	ASP-129637-13	ASP-129646-22	1	15.24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm